

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5035081

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KUMIKO KONISHI	05/17/2018
RYUUSEI FUJITA	05/17/2018
KAZUKI TANI	05/21/2018
AKIO SHIMA	05/17/2018
RECEIVING PARTY DATA	
Name:	HITACHI, LTD.
Street Address:	6-6 MARUNOUCHI 1-CHOME
Internal Address:	CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-8280
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16025656
CORRESPONDENCE DATA	
Fax Number:	(215)568-6499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	lhennessey@vklaw.com
Correspondent Name:	VOLPE AND KOENIG, P.C.
Address Line 1:	30 SOUTH 17TH STREET
Address Line 2:	SUITE 1800
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	HITACHI5-341700581US01
NAME OF SUBMITTER:	GERALD B. HALT, JR.
SIGNATURE:	/Gerald B. Halt, Jr./
DATE SIGNED:	07/03/2018
Total Attachments: 2	
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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD.,
a corporation organized under the laws of Japan,
located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8280, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD.,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SILICON CARBIDE SEMICONDUCTOR DEVICE, POWER MODULE, AND POWER CONVERSION DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI, LTD.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) <u>Kumiko Konishi</u>	(Kumiko KONISHI)	<u>5 / 17 / 2018</u>
2) <u>Ryuusei Fujita</u>	(Ryuusei FUJITA)	<u>5 / 17 / 2018</u>
3) _____	(Kazuki TANI)	_____
4) <u>Akio Shima</u>	(Akio SHIMA)	<u>5 / 17 / 2018</u>
5) _____		_____
6) _____		_____
7) _____		_____
8) _____		_____

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to be held and enjoyed by said HITACHI, LTD.,

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And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ (Kumiko KONISHI)	_____
2) _____ (Ryuusei FUJITA)	_____
3) <u>Kazuki Tani</u> (Kazuki TANI)	<u>21 / 5 / 2018</u>
4) _____ (Akio SHIMA)	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____